# Cray XC System Level Diagnosability: Commands, Utilities and Diagnostic Tools for the Next Generation of HPC Systems

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### **Overview**



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Introduction to System Diagnosability Toolkit

### Cray System Diagnosability Toolkit

- Aries High Speed Network
- Intel Processor and Co-Processor
- NVIDIA Processor
- Cabinet Power and Cooling

#### Future Directions

What is the System Diagnosability Toolkit?



- System Diagnosability is a suite of software tools designed to provide Cray field support and end customers a tool chain to quickly and reliably identify hardware and software problems in the Cray XC system.
- Diagnostics are just one aspect of the tool chain that includes BIOS, user commands, power and thermal data and event logs.
- System Diagnosability features are built into the SMW and CLE commands so that hardware and software problems can be identified at the point of failure.
- System Diagnostics validate hardware and software are executed once a problem is suspected but can be periodically scheduled.

# **System Diagnosability Toolkit**

# System Diagnosability Toolkit include:

- Command and Control tools
- Monitoring and Logging tools
- Recovery tools
- Notification tools
- System Diagnostics

## **System Diagnostics include:**

- Boot level validation and tests
- Confidence level diagnostic tests
- Stress level tests
- Performance level tests
- Workload level tests



System Diagnosability Toolkit Usage



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The right tool for the right job.

# "Once you eliminate the impossible, whatever remains, no matter how improbable, must be the truth." Sherlock Holmes

System diagnosability toolkit allows system administrators to eliminate the impossible....

# **Aries HSN Diagnosability Toolkit**



Category	Toolkit
Boot (HSS)	Power on MBIST BIOS PCIe training
Confidence (CLE)	BTE uGNI Tests: xtbte_ata and xtbte_ato FMA uGNI Tests: xtfma_ata and xtfma_ato FMA AMO uGNI Tests: xtfma_amo
Stress (CLE)	FMA & BTE Concurrent uGNI Test: xtfbc
Performance (CLE)	BTE All-To-All MPI/DMAPP Test: xta2a
Error and Data Reporting (SMW)	Linux Advanced Error Reporting (AER) PCIe Error Monitor: xtpcimon Aries Power and Thermal data

# **Aries HSN Diagnosability Toolkit Example**

#### xta2a results (no problem found)

Bytes	Min	Mean	Max	Dev	Scaled
4096	5457	5603	5668	56	1.0%

#### xta2a results (problem found)

Bytes	Min	Mean	Max	Dev	Scaled
4096	3626	4897	4891	74	1.5%
4096	3944	4916	4918	74	1.5%
4096	4068	4916	4918	74	1.5%
4096	3617	4915	4919	84	1.7%

Bandwidth low for set 994 nodes 4056 4059: 3617GB/s Bandwidth low for set 1051 nodes 4288 4291: 4012GB/s



# **Intel Processors Diagnosability Toolkit**



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Category	Toolkit
Boot (HSS)	BIOS processor, QPI, PCIe and memory
Confidence (CLE)	Processor Test: xtcpuburn Memory Tests: xtmemtester NUMA Tests: xtnumatest
Stress (CLE)	Processor Tests: xtcpudgemm
Performance (CLE)	Processor Tests: xtcpudgemm Memory Tests: xtnumatest
Error and Data Reporting (SMW)	Cray Embedded ITP scripts: xtitp MCA Errors: xthwerrlogd/xthwerrlog Intel MCA Decode: xtmcadecode Intel processor Power and Thermal data

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## Intel Processor Diagnosability Toolkit Example

### BIOS

QPI 0 Registers:. QPI Link Status: 0x0606FC00. QPI MISC Status: 3. QPI Error Counter[0]: 0x00000000.

#### xtnumatest -S 0x100 -s -l 3 -v

Running test08: \*\*\*\*\* QPI Bandwidth Test \*\*\*\*\* Expected socket 0 to socket 1 is: (22990 MB/s - 25410 MB/s) Expected socket 1 to socket 0 is: (22990 MB/s - 25410 MB/s)

#### xtitp -t c0-0c0s7 qpi-status 1

Socket 0 QPI0: Link Speed: 8.0 GT/s Configured Tx Width: Full Configured Rx Width: Full

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# Intel Co-Processors Diagnosability Toolkit



Category	Toolkit
Boot (HSS)	BIOS PCIe training
Confidence (CLE)	Co-processor Test: xtphidgemm PCIe Tests: xtphibandwidth
Stress (CLE)	Co-processor Test: xtphidgemm
Performance (CLE)	Co-processor Test: xtphidgemm
Workload (CLE)	GEMM, SHOC, and STREAMS
Error and Data Reporting (SMW)	MCA Errors: xthwerrlogd/xthwerrlog Intel MCA Decode: xtmcadecode Intel co-processor Power and Thermal data

# **Co-Processor Diagnosability Toolkit Example**

### BIOS

PciBus: KNC detected @ B3|D0|F0 PciBus: KNC [B3|D0|F0] initialized, Width: x16, CurSpd: 5.0 Gbps

#### xtbounce

\*\*\*\* node\_up \*\*\*\*
09:12:12 - Beginning to wait for response(s)
09:15:14 - Received 50 of 54 responses
ERROR: c0-0c0s8n0 - 370 – KNC PCIe link speed mismatch

#### xtphibandwidth -v -i 10

14:49:41 c0-0c0s8n0 nid00032 0, 128, 6223.58, 134184, 6481.61 14:49:41 c0-0c0s8n0 nid00032 1, 128, 6231.33, 107184, 6489.37 15:46:26 Failed:

Bandwidth actual: 107184,

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Bandwidth expected greater than: 110000

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# Nvidia GPU SXM Diagnosability Toolkit



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Toolkit
BIOS PCIe training
GPU Tests: xkdgemm GPU Memory Tests: xkmemtest PCIe Tests: xkbandwidth
GPU, Memory, PCIe Tests: xkstress
GPU Tests: xkdgemm
HPL (Single NODE GPU)
PCIe Error Monitor: xtpcimon GPU Memory Errors: xtaccecc Nvidia GPU Power and Thermal data

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**Nvidia GPU Diagnosability Toolkit Example** 



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### xkdgemm -m 12100 -n 4096 -k 14100 -i 1 -l 10 -g -v

15:08:56 c0-0c2s13n2 nid00182 MPI mode enabled, root node Iteration, GFlops, Temp, Power, P-state, SMClockrate 0, 1229.52, 44, 194.464, 0, 732

#### **On Failure:**

12:02:32 c0-0c1s5n1 nid00085 Failed: c0-0c1s5n1 nid00085 8, 1295.29, 74, 194.934, 0, 745 GFlops actual: 1295.29, GFlops expected greater than: 1300

# **Cray HSS Diagnosability Toolkit**



Category	Toolkit
Boot (HSS)	HSS Microcontroller Power on validations HSS Microcontroller Pre-boot validations HSS Microcontroller Post-boot validations
Confidence	System temp, power and status: xtcheckhss
(SMW)	HSS tests: xtcheckhss
Error and Data	HSS Faults, Errors & Warnings: xtconsumer
Reporting	System Environment Data Collections (SEDC)
(SMW)	Processor Power & Thermal data

**HSS Diagnosability Toolkit Example** 



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#### DIMM failure: xthwerrlog -f ./hwerrlog.p0-20140503t150204 –M

NodeCount ChanTypeDIMM BIT(s)c0-0c0s7n2260CORRECTABLEJ3000

#### Low Voltage Failure: xtcheckhss --volts --blade=c0-0c0s7

ComponentModuleSensorHMIN SMIN DATAUNITSMAX HMAX

c0-0c0s7n2 qpdc0\_n0\_s0\_mem\_vrm vdd\_vdr01\_s0\_c\_i 1200 1350 1339 v\*1000 1650 1800

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## **Future Considerations**



- Additional workload tests
- Additional node stress tests
- Add end-to-end storage tests including the Infiniband
- Enhanced diagnostic data analysis tools
- HSS system dashboard

### **Summary**



- Aries High Speed Network
- Intel Processors and Co-Processors
- Nvidia GPU
- HSS Cabinet Power and Cooling

#### Future focus on the HPC System

- End-to-end storage tests
- Additional Stress and workload tests
- Data Analysis tools
- System dashboard



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